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Attorney Docket No. 566.39636X00  
Serial No. 09/762,823  
5/28/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): WATANABE, et al.

Group: 2827

Serial No.: 09/762,823

Examiner: Cuneo, Kamand

Filed: April 23, 2001

For: ADHESIVE FOR BONDING CIRCUIT MEMBERS, CIRCUIT BOARD  
AND PROCESS FOR ITS PRODUCTION

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

May 20, 2002

Sir:

In response to the Office Action mailed February 20, 2002, please amend the  
above-identified application as follows:

IN THE CLAIMS:

Please amend the claims presently in the application as follows:

BI  
1. (Twice Amended) An adhesive for bonding circuit members which is to be  
put between circuit electrodes facing each other;

said circuit electrodes facing each other being pressed interposing the  
adhesive between them, to interconnect the electrodes electrically in the direction of  
pressing;

said adhesive comprising a first adhesive layer which includes an adhesive  
resin composition and an insulative inorganic filler;

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